Outsourced Semiconductor Assembly and Testing (OSAT) Market: Trends, Opportunities and Competitive Analysis [2024-2030]

https://marketpublishers.com/r/OCBAFD77F019EN.html

Date: April 2024
Pages: 150
Price: US$ 4,850.00 (Single User License)
ID: OCBAFD77F019EN

Abstracts

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Outsourced Semiconductor Assembly and Testing Market Trends and Forecast

The future of the global outsourced semiconductor assembly and testing (OSAT) market looks promising with opportunities in the automotive, telecommunication, computing & networking, consumer electronic, and industrial industries. The global outsourced semiconductor assembly and testing market is expected t%li%reach an estimated $51.4 billion by 2030 with a CAGR of 4.5% from 2024 t%li%2030. The major drivers for this market are increasing semiconductor content within electronics products t%li%provide greater functionality and higher levels of performance, growth in demand for smartphones and internet connected devices, and increasing electronic content in automotive for safety, navigation, fuel efficiency, emission reduction, and entertainment system.

Lucintel forecast that assembly & packaging will remain the largest segment over the forecast period due t%li%growing demand for telecom infrastructure and electronic products across the globe.

Within this market, consumer electronics segment is projected t%li%record the highest growth due t%li%growing acceptance of 5G technologies and increasing consumption of smart televisions, tablets, and smartphones.

Asia Pacific is expected t%li%witness the highest growth during

the forecast period due t%li%growing adoption of IoT (internet of things), increasing electronic content per vehicle, and growing industrial automation in countries, such as China, Taiwan, and India.

Asia Pacific is expected t%li%witness the highest growth

1. United States: Companies like Amkor Technology, Inc. and ASE Technology Holding Co., Ltd. drive innovation in the US OSAT market. Initiatives such as the Semiconductor Industry Association (SIA) promote collaboration and research in semiconductor manufacturing. The US government supports semiconductor R&D through agencies like the Department of Defense (DoD) and the National Science Foundation (NSF).

2. Taiwan: Taiwanese companies, including Advanced Semiconductor Engineering, Inc. (ASE) and Siliconware Precision Industries Co., Ltd. (SPIL), lead the global OSAT market. Government initiatives like the Industrial Development Bureau (IDB) support the semiconductor industry's growth and competitiveness. Taiwan Semiconductor Research Institute (TSRI) promotes R&D in semiconductor technologies.

3. China: Chinese OSAT companies like Jiangsu Changjiang Electronics Technology Co., Ltd. (JCET) and Tianshui Huatian Technology Co., Ltd. are expanding rapidly. Government initiatives such as the "Made in China 2025" plan aim t%li%strengthen the semiconductor industry's capabilities. The Ministry of Industry and Information Technology (MIIT) provides support for semiconductor manufacturing.

4. South Korea: South Korean companies like Amkor Technology Korea Inc. and Powertech Technology Inc. (PTI) are prominent players in the OSAT market. Government initiatives like the Korea Semiconductor Industry Association (KSIA) promote industry growth and innovation. The Ministry of Trade, Industry and Energy (MOTIE) supports semiconductor development initiatives.

5. Singapore: Singaporean OSAT companies, including GlobalFoundries Singapore Pte. Ltd. and UTAC Holdings Ltd., contribute significantly t%li%the global market. Government initiatives such as the Singapore Economic Development Board (EDB) support semiconductor manufacturing investments and talent development. The National Research Foundation (NRF) funds semiconductor research and development projects.

A more than 150-page report is developed t%li%help in your business decisions. Sample figures with some insights are shown below.

Outsourced Semiconductor Assembly and Testing Market (OSAT) by Segment

The study includes a forecast for the global outsourced semiconductor assembly and testing market by service type, packaging type, application, and region, as follows:

OSAT Market by Service Type [Value ($B) Shipment Analysis from 2018 t%li%2030]:

Assembly & Packaging

Testing

OSAT Market by Packaging Type [Value ($B) Shipment Analysis from 2018 t%li%2030]:

Wire Bond

Flip Chip

Wafer Level

Others

OSAT Market by Application [Value ($B) Shipment Analysis from 2018 t%li%2030]:

Automotive

Telecommunications

Computing & Networking

Consumer Electronics

Industrial

OSAT Market by Region [Value ($B) Shipment Analysis from 2018 t%li%2030]:

North America

Europe

Asia Pacific

The Rest of the World

List of Outsourced Semiconductor Assembly and Testing (OSAT) Companies

Companies in the market compete on the basis of product quality offered. Major players in this market focus on expanding their manufacturing facilities, R&D investments, infrastructural development, and leverage integration opportunities across the value chain. With these strategies outsourced semiconductor assembly and testing companies cater increasing demand, ensure competitive effectiveness, develop innovative products & technologies, reduce production costs, and expand their customer base. Some of the outsourced semiconductor assembly and testing companies profiled in this report includes.

Advanced Semiconductor

Amkor

Jiangsu Changjiang Electronics Technology

Siliconware Precision Industries

PTI (Powertech Technology Inc.)

United test and assembly center

King Yuan Electronics

ChipMOS

Recent Developments in OSAT Market

Rising Demand for Advanced Packaging Solutions: The OSAT market is experiencing growth driven by increasing demand for advanced packaging solutions such as fan-out wafer-level packaging (FOWLP) and 3D packaging technologies. These technologies enable higher performance, miniaturization, and heterogeneous integration in semiconductor devices.

Investments in Capacity Expansion: OSAT providers are investing in capacity expansion t%li%meet the growing demand for semiconductor packaging and testing services. Companies like ASE Technology Holding Co. and Amkor Technology are ramping up production facilities and acquiring advanced equipment t%li%support the industry's needs.

Technological Advancements in Test Equipment: OSAT companies are adopting advanced test equipment and methodologies t%li%improve efficiency, accuracy, and reliability in semiconductor testing processes. Innovations such as automated test handling systems and high-speed test solutions are enhancing the capabilities of OSAT providers.

Focus on Heterogeneous Integration and System Integration: OSAT vendors are increasingly involved in heterogeneous integration and system-level packaging, offering services that combine multiple chips, sensors, and passive components int%li%a single package. This trend aligns with the growing demand for integrated solutions in applications such as automotive, IoT, and artificial intelligence.

Adoption of Advanced Materials and Processes: OSAT providers are adopting advanced materials and manufacturing processes t%li%address the requirements of emerging applications such as 5G, edge computing, and high-performance computing. Technologies like advanced substrate materials, wafer-level chip-scale packaging (WLCSP), and system-in-package (SiP) are gaining traction in the market.

Features of the OSAT Market

Market Size Estimates:Outsourced semiconductor assembly and testing market size estimation in terms of value ($B)

Trend And Forecast Analysis:Market trends (2018-2023) and forecast (2024-2030) by various segments and regions.

Segmentation Analysis:Outsourced semiconductor assembly and testing market size by various segments, such as by service type, packaging type, application, and region

Regional Analysis:Outsourced semiconductor assembly and testing market breakdown by North America, Europe, Asia Pacific, and the Rest of the World.

Growth Opportunities:Analysis on growth opportunities in different by service type, packaging type, application, and regions for the outsourced semiconductor assembly and testing market.

Strategic Analysis:This includes M&A, new product development, and competitive landscape for the outsourced semiconductor assembly and testing market.

Analysis of competitive intensity of the industry based on Porter's Five Forces model.

FAQ

Q1. What is the outsourced semiconductor assembly and testing (OSAT) market size?

Answer: The global outsourced semiconductor assembly and testing (OSAT) market is expected t%li%reach an estimated $51.4 billion by 2030.

Q2. What is the growth forecast for the OSAT market?

Answer: The global outsourced semiconductor assembly and testing market is expected t%li%grow with a CAGR of 4.5% from 2024 t%li%2030.

Q3. What are the major drivers influencing the growth of the OSAT market?

Answer: The major drivers for this market are increasing semiconductor content within electronics products t%li%provide greater functionality and higher levels of performance, growth in demand for smartphones and internet connected devices, and increasing electronic content in automotive for safety, navigation, fuel efficiency, emission reduction, and entertainment system.

Q4. What are the major segments for OSAT market?

Answer: The future of the outsourced semiconductor assembly and testing market looks promising with opportunities in the automotive, telecommunication, computing & networking, consumer electronic, and industrial application industries.

Q5. Wh%li%are the key outsourced semiconductor assembly and testing companies?

Answer: Some of the key outsourced semiconductor assembly and testing companies are as follows:

Advanced Semiconductor

Amkor

Jiangsu Changjiang Electronics Technology

Siliconware Precision Industries

PTI (Powertech Technology Inc.)

United test and assembly center

King Yuan Electronics

ChipMOS

Q6. Which OSAT segment will be the largest in future?

Answer:Lucintel forecast that assembly & packaging will remain the largest segment over the forecast period due t%li%growing demand for telecom infrastructure and electronic products across the globe.

Q7. In outsourced semiconductor assembly and testing market, which region is expected t%li%be the largest in next 5 years?

Answer: Asia Pacific is expected t%li%witness the highest growth during the forecast period due t%li%growing adoption of IoT (internet of things), increasing electronic content per vehicle, and growing industrial automation in countries, such as China, Taiwan, and India.

Q8. D%li%we receive customization in this report?

Answer: Yes, Lucintel provides 10% Customization Without any Additional Cost.

This report answers following 11 key questions

Q.1. What are some of the most promising, high-growth opportunities for the global outsourced semiconductor assembly and testing market by service type (assembly & packaging and testing), packaging type (wire bond, flip chip, wafer level, and others), application (automotive, telecommunications, computing & networking, consumer electronics, and industrial), and region (North America, Europe, Asia Pacific, and the Rest of the World)?

Q.2. Which segments will grow at a faster pace and why?

Q.3. Which region will grow at a faster pace and why?

Q.4. What are the key factors affecting market dynamics? What are the key challenges and business risks in this market?

Q.5. What are the business risks and competitive threats in this market?

Q.6. What are the emerging trends in this market and the reasons behind them?

Q.7. What are some of the changing demands of customers in the market?

Q.8. What are the new developments in the market? Which companies are leading these developments?

Q.9. Wh%li%are the major players in this market? What strategic initiatives are key

players pursuing for business growth?

Q.10. What are some of the competing products in this market and how big of a threat d%li%they pose for loss of market share by material or product substitution?

Q.11. What M&A activity has occurred in the last 5 years and what has its impact been on the industry?

For any questions related t%li%outsourced semiconductor assembly and testing market or related t%li%outsourced semiconductor assembly and testing companies, outsourced semiconductor assembly and testing market size, outsourced semiconductor assembly and testing market share, outsourced semiconductor assembly and testing analysis, write Lucintel analyst at email: helpdesk@lucintel.com we will be glad t%li%get back t%li%you soon.

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